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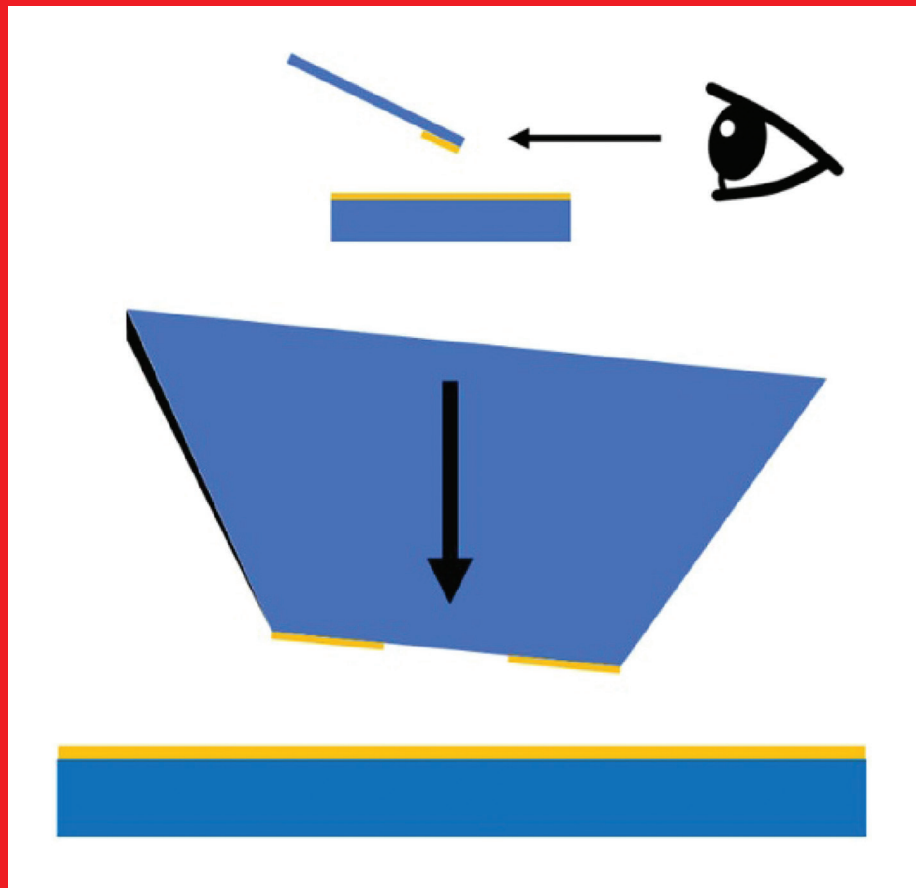
PAPERS

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Steve Arscott

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